

IN THE CLAIMS

1-13. (Canceled)

14. (New) A method of manufacturing a semiconductor device comprising the steps of:

(a) providing a first mold having a main surface, and a second mold having a main surface and provided with first and second concaved portions on the main surface;

(b) providing a resin containing plural particles;

(c) providing a sheet having a through hole having a diameter larger than that of the particles;

(d) opposing and contacting the main surface of the first mold and the main surface of the second mold and disposing the sheet between the main surface of the first mold and the main surface of the second mold to situate the first and the second concaved portions in the region where the through hole is disposed;

(e) after the step (d), injecting a resin to the inside of the openings surrounded with the main surface of the first mold and the first and second concaved portions;

(f) after the step (e), removing the sheet and the resin on the main surfaces of the first mold and the second mold;

(g) after the step (f), opposing and contacting the main surface of the first mold and the main surface of the second mold, disposing a first semiconductor chip inside of a first

opening surrounded with the main surface of the first mold and the first concaved portion, and disposing a second semiconductor chip inside of a second opening surrounded with the main surface of the first mold and the second concaved portion; and

(h) after the step (g), filling an encapsulating resin to the inside of the first opening and the second opening and encapsulating the first semiconductor chip and the second semiconductor chip with the encapsulating resin.

15. (New) A method of manufacturing a semiconductor device according to claim 14, wherein the through hole of the sheet is extended over the outside of the first concaved portion and the second concaved portion.

16. (New) A method of manufacturing a semiconductor device according to claim 15, wherein the sheet is comprised of paper.

17. (New) A method of manufacturing a semiconductor device according to claim 16, wherein the sheet has frame shape.

18. (New) A method of manufacturing a semiconductor device according to claim 14, wherein the sheet is comprised of paper.